RELIABILITY REPORT

FOR

MAX4658ESA+

PLASTIC ENCAPSULATED DEVICES

September 4, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX4658ESA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

Maxim's MAX4655-MAX4658 are medium-voltage CMOS analog switches with low on-resistance of 10 max, specifically designed to handle large switch currents. With a switch capability of up to 400mA peak current and 300mA continuous current (MAX4655/MAX4656), and up to 300mA peak current and 150mA continuous current (MAX4657/MAX4658), these parts can switch loads as low as 25 . They can replace reed relays with a million times the speed and virtually unlimited number of lifetime cycles. Normal power consumption is only 3mW, whether the switch is on or off. These parts are TTL/CMOS compatible and will switch any voltage within its power-supply range. These are SPST (single-pole/single-throw) switches. The MAX4655/MAX4657 are normally closed (NC), while the MAX4656/MAX4658 are normally open (NO). The difference between the MAX4655/MAX4656 and the MAX4657/MAX4658 is in the power dissipation of their packages. Refer to the *Absolute Maximum Ratings and the Electrical Characteristics* in the full data sheet. The MAX4655-MAX4658 power-supply range is from ±4.5V to ±20V for dual-supply operation and +9V to +40V for single-supply operation. These switches can operate from any combination of supplies, within a 40V V+ to V- range. They conduct equally well in either direction and can handle rail-to-rail analog signals. The offleakage current is only 1nA max at TA = +25°C. They are available in 8-pin µMAX®, TDFN, and SO packages, with exposed paddle options for high-power applications.

II. Manufacturing Information

A. Description/Function:	High-Current, 10 , SPST, CMOS Analog Switches
B. Process:	S5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Thailand, Malaysia
F. Date of Initial Production:	April 27, 2001

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0233
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	136°C/W
M. Multi Layer Theta Jc:	38°C/W

IV. Die Information

A. Dimensions:	64 X 54 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 76 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 14.1 \times 10^{-9}$

$\lambda = 14.1$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the S5 Process results in a FIT Rate of 0.09 @ 25C and 1.55 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AH59-1 die type has been found to have all pins able to withstand a HBM transient pulse of <+/-600 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX4658ESA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	76	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data